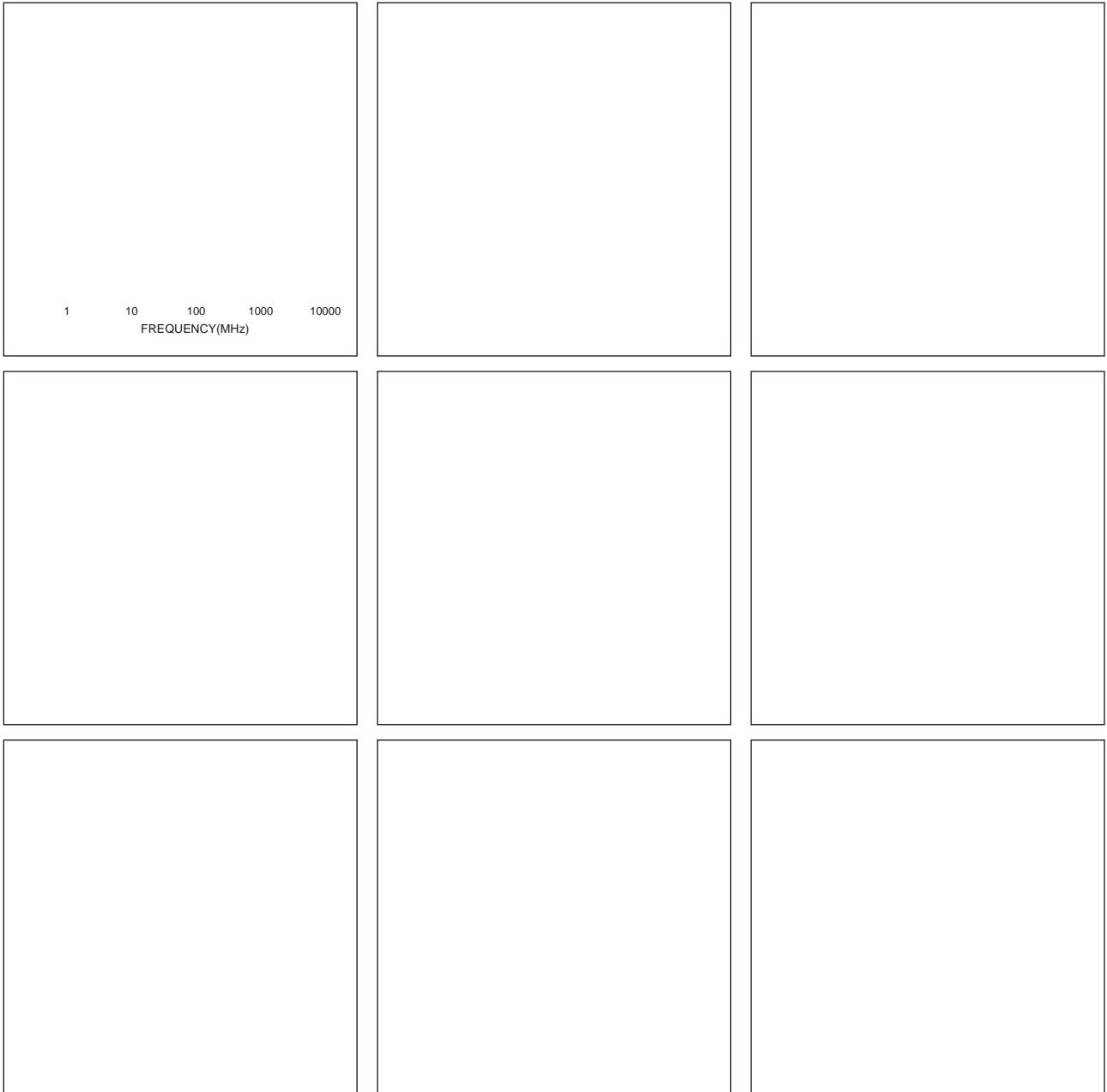
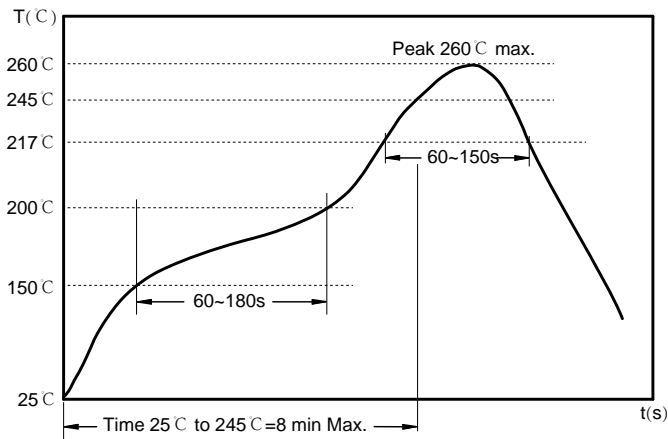


Typical Electrical Characteristics:



Soldering Reflow:



Preheat condition: 150 ~200 °C / 60~180 sec.

Allowed time above 217 °C: 60~150 sec.

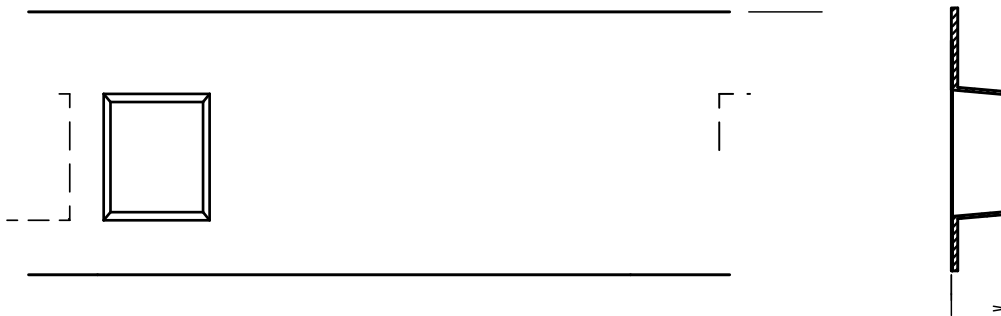
Max temperature: 260 °C.

Max time at max temperature: 10 sec.

Allowed Reflow time: 3x max.

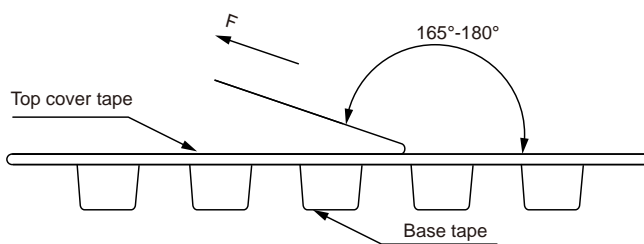
Packaging Information:

Tape Dimension :



| Series | A0 (mm) | B0 (mm) | D (mm) | P0 (mm) | P1 (mm) | W (mm) | K0 (mm) | E (mm) | T (mm) |
|----------|-----------|-----------|----------|----------|----------|----------|-----------|-----------|------------|
| BCMA2012 | 1.50± 0.1 | 2.35± 0.1 | 1.5± 0.1 | 4.0± 0.1 | 4.0± 0.1 | 8.0± 0.3 | 1.45± 0.1 | 1.75± 0.1 | 0.28± 0.05 |

Peel force of top cover tape:



The peel force of top cover tape shall be between 0.14 to 0.78 N

Reel Dimension: [mm]

